

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10714285			
<b>Filing Date:</b>	14-Nov-2003			
<b>Title of Invention:</b>	Recessed-bond semiconductor package substrate			
<b>First Named Inventor:</b>	Edgardo R. Hortaleza			
<b>Filer:</b>	Yingsheng Tung/Jackie McBride			
<b>Attorney Docket Number:</b>	TI-35932 (1962-07400)			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
Extension - 2 months with \$0 paid	1252	1	450	450

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				450